

JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO., LTD

SMAG Plastic-Encapsulate Diodes

M1 THRU M7 General Purpose Rectifier Diodes

Features

• I_{F(AV)} 1A

●VRRM 50V-1000V

High surge current capability

• Polarity: Color band denotes cathode

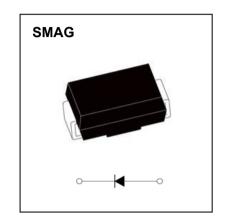
Applications

Rectifier

Marking

• MX

X: From 1 To 7



Limiting Values(Absolute Maximum Rating)

	Symbol	Unit	Test Conditions	M							
ltem				1	2	3	4	5	6	7	
Repetitive Peak Reverse Voltage	V_{RRM}	V		50	100	200	400	600	800	1000	
Maximum RMS Voltage	V _{RMS}	V		35	70	140	280	420	560	700	
Average Forward Current	I _{F(AV)}	А	60Hz Half-sine wave , Resistance load , T _L =75 ℃				1.0				
Surge(Non-repetitive)Forward Current	I _{FSM}	А	60Hz Half-sine wave , 1 cycle , Ta=25 ℃	30							
Operation Junction and Storage Temperature Range	T_{J} , T_{STG}	$^{\circ}$				-5	5 ~ +1:	50			

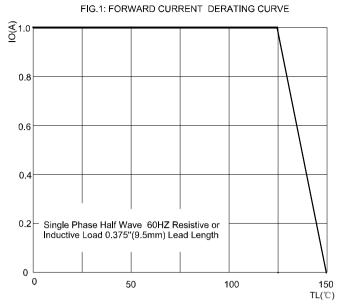
Electrical Characteristics (T=25℃ Unless otherwise specified)

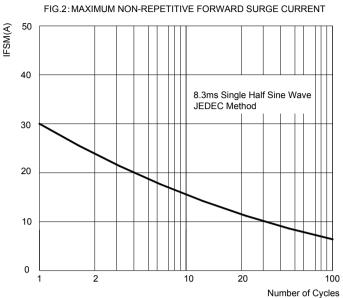
			Test Condition		M							
Item	Symbol	Unit			1	2	3	4	5	6	7	
Peak Forward Voltage	V _F	V	I _F =1.0A		1.0							
Deeds Decrees Occurrent	I _{RRM1}		\/ -\/	T _a =25℃				5				
Peak Reverse Current	I _{RRM2}	μΑ	μA V _{RM} =V _{RRM}	T _a =125℃				50				
Thermal	$R_{\theta J-A}$	°C/W	Between junction and ambient			55						
Resistance(Typical)	$R_{\theta J-L}$	C/ VV	Between junction and terminal					25				

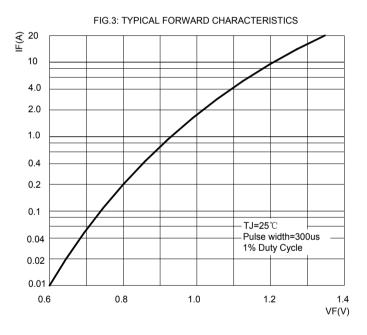
Notes:

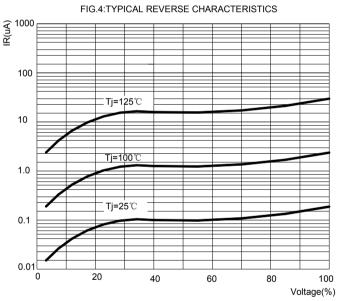
Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.2" x 0.2" (5.0 mm x 5.0 mm) copper pad areas

Typical Characteristics

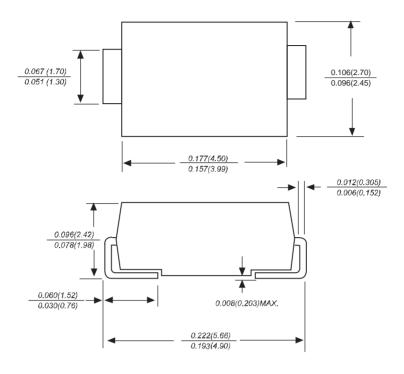






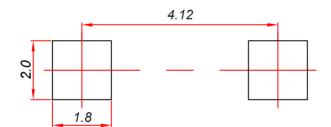


SMAG Package Outline Dimensions



Dimensions in inches and (millimeters)

SMAG Suggested Pad Layout



Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance: ± 0.05mm.
- 3. The pad layout is for reference purposes only.

NOTICE

JSCJ reserves the right to make modifications,enhancements,improvements,corrections or other changes without further notice to any product herein. JSCJ does not assume any liability arising out of the application or use of any product described herein.

Reel Taping Specifications For Surface Mount Devices-SMAG

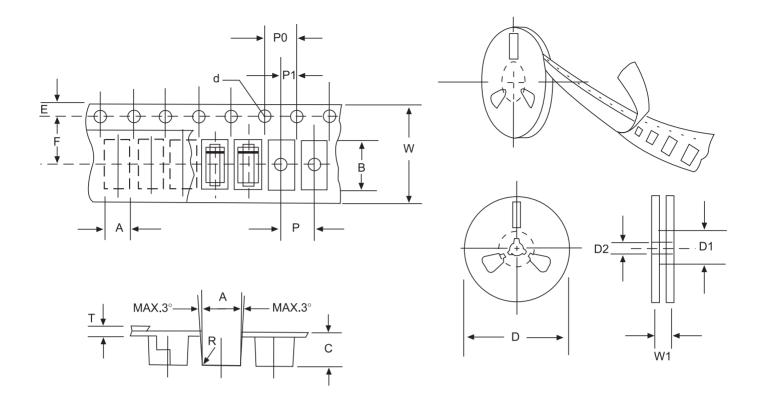


FIG: CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING

ITEM	SYMBOL SMAG mm(inch)			
Carrier width	А	2.79±0.1(0.110±0.004)		
Carrier length	В	5,33±0.1(0,210±0,004)		
Carrier depth	С	2.36±0.1(0.093±0.004)		
Sprocket hole	d	1.55±0.05 (0.061±0.002)		
Reel outside diameter	D	279±2.0 (11±0.079)		
Reel inner diameter	D1	75±1.0 (2.95±0.039)		
Feed hole diameter	D2	13±0.5(0.512±0.020)		
Strocket hole position	E	1.75±0.1(0.069±0.004)		
Punch hole position	F	5.5±0.05(0.217±0.002)		
Punch hole pitch	Р	4.0±0.1(0.157±0.004)		
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)		
Embossment center	P1	2.0±0.1(0.079±0.004)		
Totall tape thickness	Т	0.28±0.02(0.011±0.0008)		
Tape width	W	12.0±0.2(0.472±0.008)		
Reel width	W1	16.8±2.0(0.661±0.079)		

NOTE: Devices are packed in accordance with EIA standard RS-481-A and specification given above.

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